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DRG. NO. B-2496

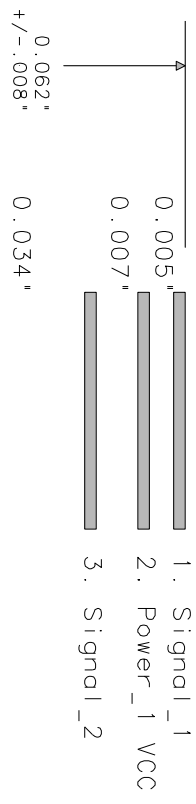
SH 1 REF B

1

D

D

74.000±.100
mm



C

C

149.000±.100
mm



B

B

BOARD'S DRILL SCHEDULE

FHS [Inches]	COUNT	PLATED	COMMENT
.016	104	YES	
.02	387	YES	
.041	103	YES	
.042	80	YES	
.0561	4	NO	
.057	2	YES	
.1063	8	NO	

A

A

Board Characteristics

- Dimensions are given in inches and mm;
- Material FR4;
- Min trace width: 0.006" on all layers;
- Min. clearance: 0.006" on all layers;
- 1 oz copper for top, bottom and power layers;
- 1/2 oz copper for embedded signal layers;
- Electroless Nickel/Immersion Gold plating. Apply soldermask;
- FHS tolerances: 0.002";
- Board thickness and inter-layer spacing as specified;
- Silkscreen on both sides;
- Trace impedance: 55 Ohm +/-5 Ohm for 0.006" traces on all layers;

THIS SHEET IS COMPUTER GENERATED

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1

QUESTIONS SPECIFIED DIMENSIONS ARE IN INCHES UNLESS OTHERWISE SPECIFIED		CONTRACT NO.		The University of Chicago Electronics Development Group	
FRACCTIONS DECIMALS	XX	APPROVALS	DATE	TITLE	
ON NOT SCALE DRAWINGS	XX	DRAM M. Bogdan	10/10/02	CDF Level 2 cmctx Board	
FINISH		CHECKED H. Sander's	10/10/02	SIZE FSCM NO.	DRG. NO. B-2496
SIMILAR TO		ISSUED		SCALE	SHEET 1/1